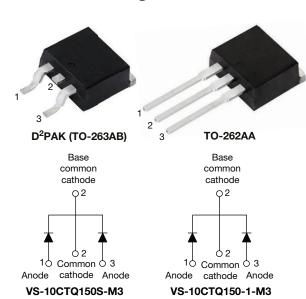
VS-10CTQ150S-M3, VS-10CTQ150-1-M3

Vishay Semiconductors

High Performance Schottky Rectifier, 2 x 5 A



PRIMARY CHARACTERISTICS						
I _{F(AV)} 2 x 5 A						
V_{R}	150 V					
V _F at I _F	0.93 V					
I _{RM}	7 mA at 125 °C					
T _J max.	175 °C					
E _{AS}	5 mJ					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Common cathode					

FEATURES

- 175 °C T_J operation
- Center tap configuration
- · Low forward voltage drop
- High frequency operation



- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

This center tap Schottky rectifier has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL CHARACTERISTICS VALUES UNITS								
I _{F(AV)}	Rectangular waveform	10	A					
V _{RRM}		150	V					
I _{FSM}	t _p = 5 μs sine	620	Α					
V _F	5 A _{pk} , T _J = 125 °C (per leg)	0.73	V					
T_J	Range	-55 to +175	°C					

VOLTAGE RATINGS							
PARAMETER SYMBOL VS-10CTQ150S-M3 VS-10CTQ150-1-M3 UNITS							
Maximum DC reverse voltage	V _R	150	V				
Maximum working peak reverse voltage	V_{RWM}	150	V				



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ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST COND	ITIONS	VALUES	UNITS				
Maximum average per leg	1	50 % duty ovalo at T 155 °C	rootongular wayafarm	5					
forward current, see fig. 5 per device	I _{F(AV)}	50 % duty cycle at T _C = 155 °C, rectangular waveform		10	Α				
Maximum peak one cycle non-repetitive		5 μs sine or 3 μs rect. pulse	Following any rated load	620	А				
surge current per leg, see fig. 7	I _{FSM}	10 ms sine or 6 ms rect. pulse	condition and with rated V _{RRM} applied	115					
Non-repetitive avalanche energy per leg	E _{AS}	$T_J = 25 ^{\circ}\text{C}, I_{AS} = 1 \text{A}, L = 10 \text{mH}$		5	mJ				
Repetitive avalanche current per leg	I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T _J maximum V _A = 1.5 x V _B typical		1	Α				

ELECTRICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS			
		5 A	T 05 %C	0.93	V			
Maximum forward voltage drop per leg) (1)	10 A	- T _J = 25 °C	1.10				
See fig. 1	V _{FM} ⁽¹⁾	5 A	T 105 °C	0.73				
		10 A	- T _J = 125 °C	0.86				
Maximum reverse leakage current per	I _{RM} ⁽¹⁾	T _J = 25 °C	V Datad V	0.05	- mA			
leg See fig. 2		T _J = 125 °C	V _R = Rated V _R	7				
Threshold voltage	V _{F(TO)}	T T '	•	0.468	V			
Forward slope resistance				28	mΩ			
Maximum junction capacitance per leg	C _T	V _R = 5 V _{DC} (test signal range	200	pF				
Typical series inductance per leg	L _S	Measured lead to lead 5 mm	8.0	nH				
Maximum voltage rate of change	dV/dt	Rated V _B	Rated V _R					

Note

 $^{^{(1)}}$ Pulse width $< 300 \ \mu s$, duty cycle $< 2 \ \%$

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	PARAMETER		TEST CONDITIONS	VALUES	UNITS				
Maximum junction and st temperature range	orage	T _J , T _{Stg}		-55 to +175	°C				
Maximum thermal resista junction to case per leg	nce,	R _{thJC}	DC operation	3.50					
Maximum thermal resistance, junction to case per package		□thJC	DC Operation	1.75	°C/W				
Typical thermal resistance case to heatsink (only for		R _{thCS}	Mounting surface, smooth and greased	0.50					
Approximate weight				2	g				
Approximate weight				0.07	oz.				
Mounting torque	Manusticantona			6 (5)	kgf · cm				
Mounting torque	maximum			12 (10)	(lbf · in)				
Marking device			Case style D ² PAK (TO-263AB)	10CTQ1	50S				
			Case style TO-262AA	10CTQ1	50-1				



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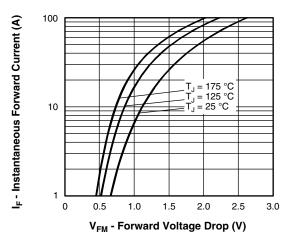
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 $T_J = 175$ °C

125

150

 $T_J = 150 \, ^{\circ}C$



I_R - Reverse Current (mA) 0.01 = 75 °C T_J = 50 °C 0.001 = 25 °C 0.0001 25 75 50 100

100

10

0.1

Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

V_R - Reverse Voltage (V)

T_J = 125 °C

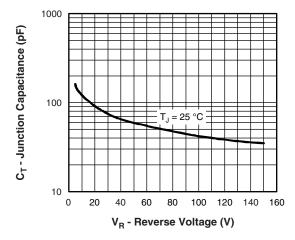


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

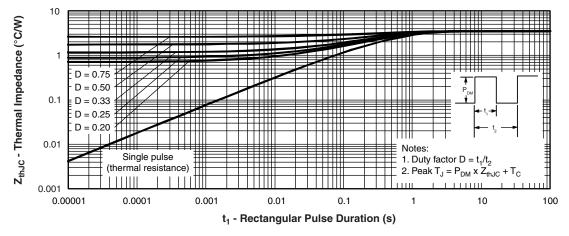


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics (Per Leg)

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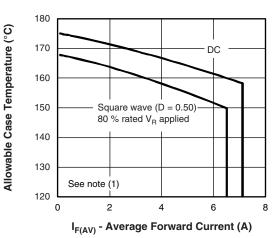


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

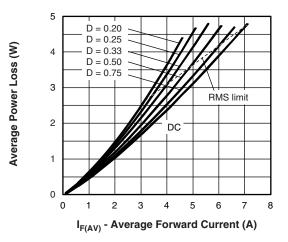


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

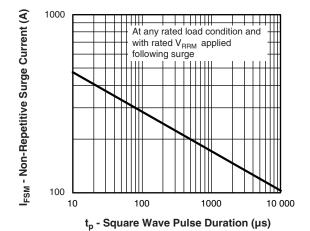


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

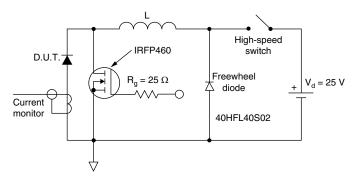


Fig. 8 - Unclamped Inductive Test Circuit

Note

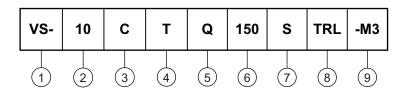
 $^{(1)}$ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{th,JC};$ $Pd = forward power loss = I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); $Pd_{REV} = inverse power loss = V_{R1} \times I_R$ (1 - D); I_R at $V_{R1} = 10 \ V$

VS-10CTQ150S-M3, VS-10CTQ150-1-M3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (10 A)

- Circuit configuration: C = common cathode

4 - T = TO-220

5 - Schottky "Q" series

Voltage rating (150 = 150 V)

7 - • S = D^2PAK (TO-263AB)

• -1 = TO-262AA

8 - • None = tube (50 pieces)

• TRL = tape and reel (left oriented - for D²PAK (TO-263AB) only)

• TRR = tape and reel (right oriented - for D²PAK (TO-263AB) only)

9 - -M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N BASE QUANTITY PACKAGING DESCRIPTION							
VS-10CTQ150S-M3	50	Antistatic plastic tubes					
VS-10CTQ150STRL-M3	800	13" diameter plastic tape and reel					
VS-10CTQ150STRR-M3	800	13" diameter plastic tape and reel					
VS-10CTQ150-1-M3	50	Antistatic plastic tubes					

LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164				
Differsions	TO-262AA	www.vishay.com/doc?96165				
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
Fait marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information		www.vishay.com/doc?96424				



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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		ES NOTES		TES SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	JIES STWIBUL	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100) BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

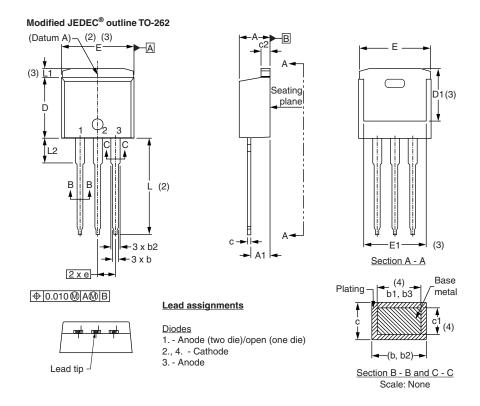
- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



Vishay Semiconductors

TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	INCHES		
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
E	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54 BSC		0.10	D BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.36	3.71	0.132	0.146		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

Revision: 11-Jul-2019 1 Document Number: 95419



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